2.5 V/3.3 V Any Level Positive Input to -2.5 V/-3.3 V LVNECL Output Translator

Description

The NB100LVEP91 is a triple any level positive input to NECL output translator. The device accepts LVPECL, LVTTL, LVCMOS, HSTL, CML or LVDS signals, and translates them to differential LVNECL output signals (-2.5 V/-3.3 V).

To accomplish the level translation the LVEP91 requires three power rails. The V_{CC} pins should be connected to the positive power supply, and the V_{EE} pin should be connected to the negative power supply. The GND pins are connected to the system ground plane. Both V_{EE} and V_{CC} should be bypassed to ground via 0.01 μF capacitors.

Under open input conditions, the \overline{D} input will be biased at $V_{CC}/2$ and the D input will be pulled to GND. These conditions will force the Q outputs to a low state, and Q outputs to a high state, which will ensure stability.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- Maximum Input Clock Frequency > 2.0 GHz Typical
- Maximum Input Data Rate > 2.0 Gb/s Typical
- 500 ps Typical Propagation Delay
- Operating Range: V_{CC} = 2.375 V to 3.8 V;
 V_{EE} = -2.375 V to -3.8 V; GND = 0 V
- Q Output will Default LOW with Inputs Open or at GND
- Pb-Free Packages are Available*



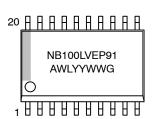
ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS*



SO-20 WB DW SUFFIX CASE 751D





24 PIN QFN MN SUFFIX CASE 485L



A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

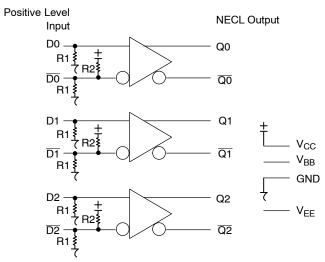


Figure 1. Logic Diagram

Table 1. PIN DESCRIPTION

F	Pin			Default	
SOIC	QFN	Name	I/O	State	Description
1, 20	3, 4, 12	V _{CC}	-	-	Positive Supply Voltage. All $V_{\rm CC}$ Pins must be Externally Connected to Power Supply to Guarantee Proper Operation.
10	15, 16	V _{EE}	-	-	Negative Supply Voltage. All V_{EE} Pins must be Externally Connected to Power Supply to Guarantee Proper Operation.
14, 17	19, 20, 23, 24	GND	-	=	Ground.
4, 7	7, 11	V_{BB}	-	_	ECL Reference Voltage Output
2, 5, 8	5, 8, 13	D[0:2]	LVPECL, LVDS, LVTTL, LVCMOS, CML, HSTL Input	Low	Noninverted Differential Inputs [0:2]. Internal 75 k Ω to GND.
3, 6, 9	6, 9, 14	D[0:2]	LVPECL, LVDS, LVTTL,LVCMOS, CML, HSTL Input	High	Inverted Differential Inputs [0:2]. Internal 75 k Ω to GND and 75 k Ω to V $_{CC}$. When Inputs are Left Open They Default to (V $_{CC}$ – GND) / 2.
19,16,13	2, 22, 18	Q[0:2]	LVNECL Output	-	Noninverted Differential Outputs [0:2]. Typically Terminated with 50 Ω to V _{TT} = V _{CC} – 2 V
18,15,12	1, 21, 17	Q[0:2]	LVNECL Output	=	Inverted Differential Outputs [0:2]. Typically Terminated with 50 Ω to V_{TT} = V_{CC} – 2 V
11	10	NC	-	-	No Connect. The NC Pin is NOT Electrically Connected to the Die and may Safely be Connected to Any Voltage from $V_{\mbox{\footnotesize{EE}}}$ to $V_{\mbox{\footnotesize{CC}}}.$
N/A	_	EP	_		Exposed Pad. (Note 1)

The thermally conductive exposed pad on the package bottom (see case drawing) must be attached to a heat sinking conduit and may only be electrically connected to V_{EE} (not GND).

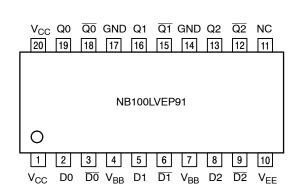


Figure 2. SOIC-20 Lead Pinout (Top View)*

*All V_{CC} , V_{EE} and GND pins must be externally connected to a power supply.

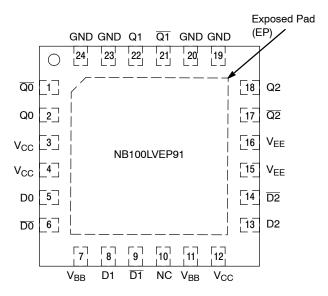


Figure 3. QFN-24 Lead Pinout (Top View)*

*All V_{CC}, V_{EE} and GND pins must be externally connected to a power supply. The thermally conductive exposed pad on the package bottom (see case drawing) must be attached to a sufficient heat–sinking conduit and may only be electronically connected to V_{EE} (not GND).

Table 2. ATTRIBUTES

Characteristic	Va	lue			
Internal Input Pulldown Resistor	(R1)	75 kΩ			
Internal Input Pullup Resistor	(R2)	75	kΩ		
ESD Protection	> 2 kV > 150 V > 2 kV				
Moisture Sensitivity (Note 2)		Pb Pkg	Pb-Free Pkg		
	SO-20 WB QFN-24	Level 1 Level 1	Level 3 Level 1		
Flammability Rating	UL 94 V-0 @ 0.125 in				
Transistor Count	446 D	evices			
Meets or exceeds JEDEC Spec EIA/Ji	ESD78 IC Latchup Test				

2. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		3.8 to 0	V
V _{EE}	Negative Power Supply	GND = 0 V		-3.8 to 0	V
VI	Positive Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	3.8 to 0	V
V _{OP}	Operating Voltage	GND = 0 V	V _{CC} – V _{EE}	7.6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	PECL V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) JESD 51-3 (1S-Single Layer Test Board)	0 lfpm 500 lfpm	SOIC-20 SOIC-20	90 60	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient) JESD 51-6 (2S2P Multilayer Test Board) with Filled Thermal Vias	0 lfpm 500 lfpm	QFN-24 QFN-24	37 32	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-20 QFN-24	30 to 35 11	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free			225 225	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC CHARACTERISTICS POSITIVE INPUTS $V_{CC} = 2.5 \text{ V}$, $V_{EE} = -2.375 \text{ to } -3.8 \text{ V}$, GND = 0 V (Note 3)

			-	-40°C			25°C		;	85°C		
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	Positive Power Supply Current		10	14	20	10	14	20	10	14	20	mA
V _{IH}	Input HIGH Voltage (Single-Ended)		1335		V _{CC}	1335		V _{CC}	1335		V_{CC}	mV
V _{IL}	Input LOW Voltage (Single-Ended)		GND		875	GND		875	GND		875	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)		0		2.5	0		2.5	0		2.5	٧
I _{IH}	Input HIGH Current (@ V _{IH})				150			150			150	μΑ
I _{IL}	Input LOW Current (@ V _{IL})	D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Input parameters vary 1:1 with V_{CC} . V_{CC} can vary +1.3 V / -0.125 V. 4. V_{IHCMR} min varies 1:1 with GND. V_{IHCMR} max varies 1:1 with V_{CC} .

Table 5. DC CHARACTERISTICS POSITIVE INPUT V_{CC} = 3.3 V; V_{EE} = -2.375 V to -3.8 V; GND = 0 V (Note 5)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	Positive Power Supply Current	10	16	24	10	16	24	10	16	24	mA
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		V_{CC}	2135		V_{CC}	2135		V_{CC}	mV
V _{IL}	Input LOW Voltage (Single-Ended)	GND		1675	GND		1675	GND		1675	mV
V _{BB}	PECL Output Voltage Reference	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 6)	0		3.3	0		3.3	0		3.3	V
I _{IH}	Input HIGH Current (@ V _{IH})			150			150			150	μΑ
I _{IL}	Input LOW Current (@ V_{IL}) $\frac{D}{D}$	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input parameters vary 1:1 with V_{CC} . V_{CC} can vary +0.5 / -0.925 V.
- 6. V_{IHCMR} min varies 1:1 with GND. V_{IHCMR} max varies 1:1 with V_{CC} .

Table 6. DC CHARACTERISTICS NECL OUTPUT $V_{CC} = 2.375 \text{ V}$ to 3.8 V; $V_{EE} = -2.375 \text{ V}$ to -3.8 V; GND = 0 V (Note 7)

			-40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
I _{EE}	Negative Power Supply Current	40	50	60	38	50	68	38	50	68	mA	
V _{OH}	Output HIGH Voltage (Note 8)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV	
V _{OL}	Output LOW Voltage (Note 8)	-1945	-1770	-1600	-1945	-1770	-1600	-1945	-1770	-1600	mV	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 7. Output parameters vary 1:1 with GND.
- 8. All loading with 50 Ω resistor to GND 2.0 V.

Table 7. AC CHARACTERISTICS $V_{CC} = 2.375 \text{ V}$ to 3.8 V; $V_{EE} = -2.375 \text{ V}$ to -3.8 V; GND = 0 V

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{OUTPP}		575 525 300	800 750 600		600 525 250	800 750 550		550 400 150	800 750 500		mV
t _{PLH} t _{PHL0}	Propagation Delay Differential D to Q Single-Ended	375 300	500 450	600 650	375 300	500 450	600 675	400 300	550 500	650 750	ps
t _{SKEW}	Pulse Skew (Note 10) Output-to-Output (Note 11) Part-to-Part (Diff) (Note 11)		15 25 50	75 95 125		15 30 50	75 105 125		15 30 70	80 105 150	ps
t _{JITTER}	RMS Random Clock Jitter (Note 12) $f_{in} = 2.0 \text{ GHz}$ Peak-to-Peak Data Dependant Jitter $f_{in} = 2.0 \text{ Gb/s}$ (Note 13)		0.5 20	2.0		0.5 20	2.0		0.5 20	2.0	ps
V _{INPP}	Input Voltage Swing (Differential Configuration) (Note 14)	200	800	1200	200	800	1200	200	800	1200	mV
t _r , t _f	Output Rise/Fall Times @ 50 MHz (20% - 80%) Q, \overline{Q}	75	150	250	75	150	250	75	150	275	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 9. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to GND 2.0 V. Input edge rates 150 ps (20% 80%).
- 10. Pulse Skew = $|\bar{t}_{PLH} t_{PHL}|$
- 11. Skews are valid across specified voltage range, part-to-part skew is for a given temperature.
- 12. RMS Jitter with 50% Duty Cycle Input Clock Signal.
 13. Peak-to-Peak Jitter with input NRZ PRBS 2³¹⁻¹ at 2.0 Gb/s.
- 14. Input voltage swing is a single-ended measurement operating in differential mode. The device has a DC gain of ≈ 50.

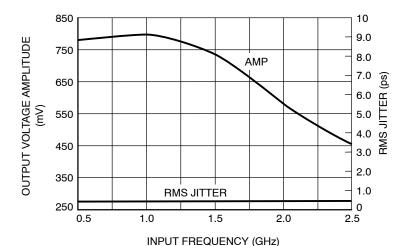


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (fin) at Ambient Temperature (Typical)

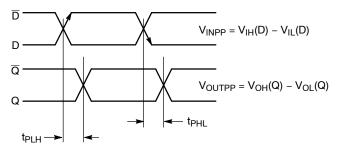


Figure 5. AC Reference Measurement

Application Information

All NB100LVEP91 inputs can accept LVPECL, LVTTL, LVCMOS, HSTL, CML, or LVDS signal levels. The limitations for differential input signal (LVDS, HSTL, LVPECL, or CML) are the minimum input swing of 150 mV

Figure 6. Standard LVPECL Interface

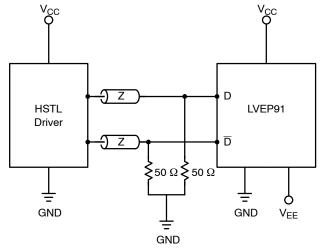


Figure 8. Standard HSTL Interface

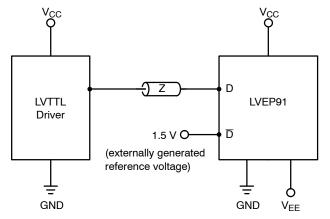


Figure 10. Standard LVTTL Interface

and the maximum input swing of 3.0 V. Within these conditions, the input voltage can range from V_{CC} to GND. Examples interfaces are illustrated below in a 50 Ω environment (Z = 50 Ω)

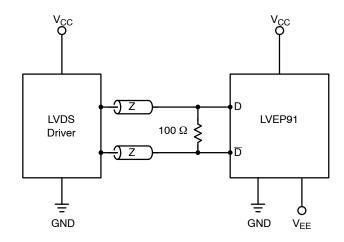


Figure 7. Standard LVDS Interface

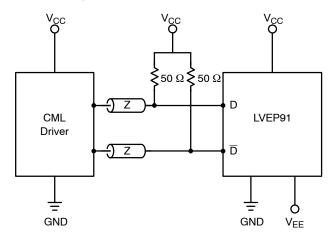


Figure 9. Standard 50 Ω Load CML Interface

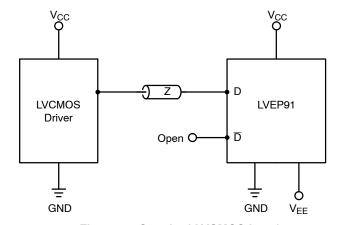


Figure 11. Standard LVCMOS Interface (\overline{D} will default to $V_{CC}/2$ when left open. A reference voltage of $V_{CC}/2$ should be applied to D input, if \overline{D} is interfaced to CMOS signals.)

ORDERING INFORMATION

Device	Package	Shipping [†]
NB100LVEP91DW	SO-20	38 Units / Rail
NB100LVEP91DWG	SO-20 (Pb-Free)	38 Units / Rail
NB100LVEP91DWR2	SO-20	1000 / Tape & Reel
NB100LVEP91DWR2G	SO-20 (Pb-Free)	1000 / Tape & Reel
NB100LVEP91MN	QFN-24	92 Units / Rail
NB100LVEP91MNG	QFN-24 (Pb-Free)	92 Units / Rail
NB100LVEP91MNR2	QFN-24	3000 / Tape & Reel
NB100LVEP91MNR2G	QFN-24 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

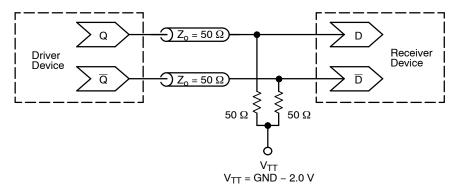


Figure 12. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design
AND8002/D - Marking and Date Codes

,

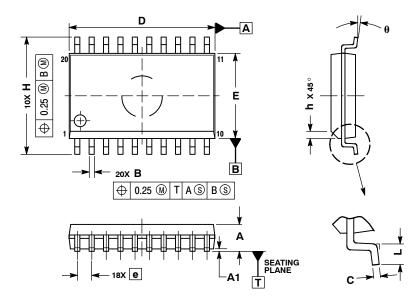
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SO-20 WB CASE 751D-05 **ISSUE G**

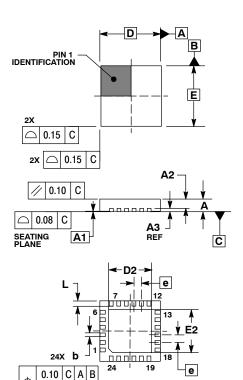


- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS
DIM	MIN	MAX
Α	2.35	2.65
A1	0.10	0.25
В	0.35	0.49
С	0.23	0.32
D	12.65	12.95
E	7.40	7.60
е	1.27	BSC
Н	10.05	10.55
h	0.25	0.75
L	0.50	0.90
Δ	00	70

PACKAGE DIMENSIONS

QFN 24 MN SUFFIX 24 PIN QFN, 4x4 CASE 485L-01 **ISSUE 0**



NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM
- FROM TERMINAL.

 COPLANARITY APPLIES TO THE EXPOSED PAD
 AS WELL AS THE TERMINALS.

	MILLIMETERS							
DIM	MIN	MAX						
Α	0.80	1.00						
A1	0.00	0.05						
A2	0.60	0.80						
A3	0.20	REF						
b	0.23	0.28						
D	4.00	BSC						
D2	2.70	2.90						
E	4.00	BSC						
E2	2.70	2.90						
е	0.50	BSC						
L	0.35	0.45						

ECLinPS is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

0.05

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

NB100LVEP91/D